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592

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# Computer Engineering and Technology

19th CCF Conference, NCCET 2015  
Hefei, China, October 18–20, 2015  
Revised Selected Papers

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# Preface

We are pleased to present the proceedings of the 19th Annual Conference on Computer Engineering and Technology (NCCET 2015). Over its short 19-year history, NCCET has established itself as one of the major national conferences dedicated to important and emerging challenges in the field of computer engineering and technology. Following previous successful events, NCCET 2015 provided a forum for bringing together researchers and practitioners from academia and industry to discuss cutting-edge research on computer engineering and technology.

We are delighted that the conference continues to attract high-quality submissions from a diverse and national group of researchers. This year, we received 158 paper submissions, among which 18 papers were accepted. Each paper received three or four peer reviews from our Technical Program Committee (TPC) comprising a total of 61 TPC members from academia, government, and industry.

The pages of this volume represent only the end result of an enormous endeavor involving hundreds of people. Almost all this work is voluntary, with some individuals contributing hundreds of hours of their time to the effort. Together, the 61 members of the TPC, the 16 members of the External Review Committee (ERC), and the 13 other individual reviewers consulted for their expertise wrote nearly 500 reviews.

Every paper received at least two reviews and many had three or more. With the exception of submissions by the TPC, each paper had at least two reviews from the TPC and at least one review from an outside expert. For the second year running most of the outside reviews were done by the ERC, which was selected in advance, and additional outside reviews beyond the ERC were requested whenever appropriate or necessary. Reviewing was “first read double-blind,” meaning that author identities were withheld from reviewers until they submitted a review. Revealing author names after the initial reviews were written allowed reviewers to find related and previous material by the same authors, which helped greatly in many cases in understanding the context of the work, and also ensured that the author feedback and discussions at the PC meeting could be frank and direct. For the first time in many years, we allowed PC members to submit papers to the conference. Submissions co-authored by a TPC member were reviewed exclusively by the ERC and other outside reviewers, and these same reviewers decided whether to accept the PC papers; no PC member reviewed a TPC paper, and no TPC papers were discussed at the TPC meeting.

After the reviewing was complete, the PC met at the National University of Defense Technology, Changsha, during May 25–28 to select the program. Separately, the ERC decided on the PC papers in e-mail and phone discussions. In the end, 18 of the 158 submissions (11 %) were accepted for the conference.

First of all, we would like to thank all researchers who submitted manuscripts. Without these submissions, it would be impossible to provide such an interesting technical program. We thank all PC members for helping to organize the conference program. We thank all TPC members for their tremendous time and efforts during the

paper review and selection process. The efforts of these individuals were crucial in constructing our successful technical program. Last but not least, we would like to thank the organizations and sponsors that supported NCCET 2015. Finally, we thank all the participants of the conference.

December 2015

Weixia Xu  
Huaguo Liang  
Minxuan Zhang  
Liquan Xiao

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